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MA6X126 (MA126)

Silicon epitaxial planar type

For switching circuit

■ Features

- Four isolated elements contained in one package, allowing highdensity mounting
- High breakdown voltage: $V_R = 80 \text{ V}$

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Reverse voltage	V_R	80	V	
Maximum peak reverse voltage	V_{RM}	80	V	
Forward current *1	I_{F}	100	mA	
Peak forward current *1	I_{FM}	225	mA	
Non-repetitive peak forward surge current *1, 2	I_{FSM}	500	mA	
Junction temperature	T_{j}	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	

Note) *1: Value for single diode

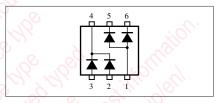
*2: t = 1 s

■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

2.90 ^{+0.20} 1.90.1 (0.95) (0.95) 4 5 6 8 8 8 8 8 8 8 8 8 8 8 8 8 8 8 8 8 8	0.16 ^{+0.10} Unit: mm
0.30+0.10 9	· III
0.50 ^{+0.10} 10°	
N-1 8-1 8-1	T. (8)
+ + + + + + + + + + + + + + + + + + +	1: Anode 3, 4 2: Anode 1
10000	3: Anode 2 4: Cathode 1, 2
o ot	5: Cathode 3 6: Cathode 4
EIAJ: SC-74	Mini6-G1 Package
	· ·

Marking Symbol: M2S

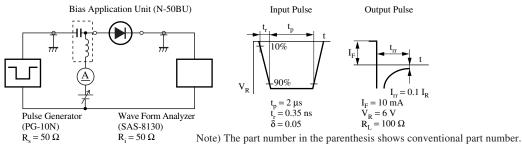
Internal Connection



Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _F	$I_F = 100 \text{ mA}$	VI)	·	1.2	V
Reverse voltage	V_R	$I_R = 100 \mu A$	80	80.		V
Reverse current	I_R	V _R = 75 V	300	,	100	nA
Terminal capacitance	C _{t1} *1	$V_R = 0 V, f = 1 MHz$	1.6		15	pF
	C _{t2} *2	6. 1160			2	
Reverse recovery time *3	t _{rr1} *1	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$			10	ns
	t _{rr2} *2	$I_{rr} = 0.1 I_R$, $R_L = 100 \Omega$			3	

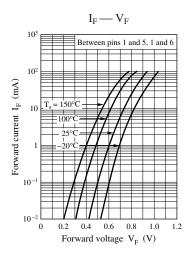
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

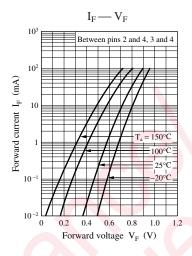
- 2. Absolute frequency of input and output is 100 MHz.
- 3. *1: Between pins 1 and 5, Between pins 1 and 6
 - *2: Between pins 4 and 2, Between pins 4 and 3
 - *3: t_{rr} measurement circuit

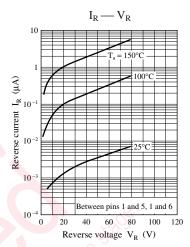


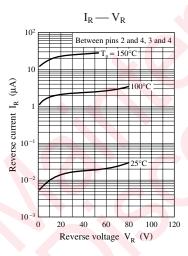
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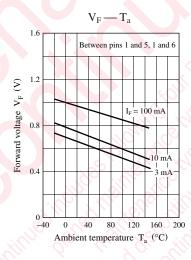
Panasonic

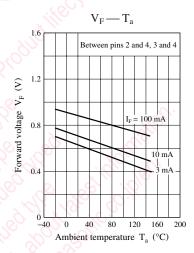


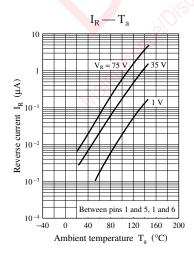


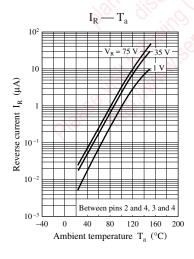


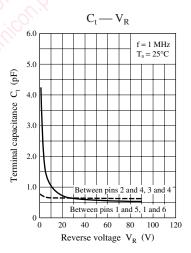




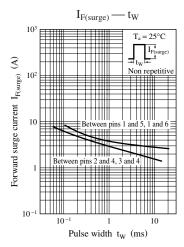








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